

**DuPont™ Teflon® AF amorphous fluoropolymers**

Teflon® AF has the lowest known dielectric constant of any known solid polymer; is optically clear, resistant to creep under stress loads, and has ability for glass transition temperatures (Tg) to be tailored for desired end use characteristics.

**DuPont Microlithographic Polymer Films (MPF)**

Permanent and non-permanent dry photoresist films for wafer bumping, MEMS and other specialty uses.

**DuPont™ GreenTape™ Low Temperature Co-fired Ceramics (LTCC)**

Provides the best combination of properties including reduced total system cost, high frequency performance, embedded passives, faster time to market, and more feature sets per given package/substrate size.

**DuPont™ Vacrel® dry film soldermask**

Provides highly reliable environmental protection through excellent electrical, chemical and mechanical properties.

**DuPont™ ImageMaster™ diazo phototooling film**

New, universal diazo phototooling film for all printed circuit board applications; combines excellent chemical resistance with superior optical and physical characteristics.

**Idealine™ silver phototooling films**

Newest generation of silver halide phototooling films; offers unsurpassed line edge quality, precise control, reliable performance and simple processing.

**DuPont™ Riston® dry film photoresist**

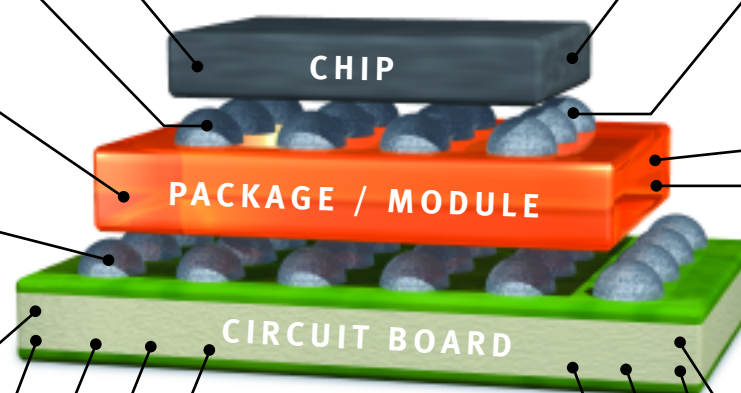
Industry standard for broad process latitude and high yield; new formulations continuously developed for leading-edge patterning in advanced packaging and modules.

**DuPont™ Mylar® polyester film**

A unique combination of physical, chemical and optical properties make these films well suited for dry film resists and flexible circuits where soldering is not required.

**DuPont™ Teflon® PTFE dispersions and films**

PTFE dispersions are applied to glass fabrics used in printed circuit board substrates and provide stable low dielectric constants over a wide temperature and frequency range.



**DuPont liquid polyimides**

Broadest portfolio of liquid polyimides in the industry; ideal for a variety of uses for advanced packaging lithography, such as wafer bumping, C-4 and redistribution, as well as sacrificial layers, flexible membranes and dielectric layers in MEMS devices.

**EKC cleaners and removers**

The industry standard for back end of line interconnect cleaning, these products remove resists used in C4 and other fine pitch wafer bumping processes and for rework of polyimides. EKC removers assure clean removal with no residues, work faster at lower temperatures and have longer bath life.

**DuPont™ Zenite® LCP resins**

Zenite® offers a superior combination of heat resistance in lead-free soldering and excellent cavity filling, even in fine pitch design. Recommended for applications requiring high temperature performance, retention of properties over a wide temperature range, dimensional stability, chemical resistance, and excellent electrical properties.

**DuPont™ Interra™ embedded passives**

A complete family of embedded passive materials and technology allowing functionality of surface mounted capacitors and resistors to be embedded for applications ranging from discrete decoupling capacitors to power/ground plane applications to termination resistors.

**DuPont™ Pyralux® flexible circuit materials**

Broadest industry portfolio for flexible and rigid-flex circuit materials including copper-clad laminates, coverlays, bondplys and sheet adhesives. Available in a range of copper, dielectric, and adhesive thicknesses.

**DuPont thick film hybrid materials**

Enables production of integrated, low-cost hermetic multichip hybrid modules on alumina, alumina nitride and beryllium oxide. Ideal for high-performance applications requiring low-resistivity metallizations, large numbers of inputs/outputs and high thermal conductivity.

**DuPont™ Thermount® non-woven aramid**

An alternative to glass reinforcement for laminates and prepregs used in high-density circuit boards and packages.

**DuPont™ Kapton® polyimide film**

Industry standard in fine pitch flexible circuit applications, spanning aerospace to consumer electronics; tailored modulus, CTE and other performance features are available.